

# INTERNATIONAL DIRECTORY OF DISPENSING SYSTEM VENDORS

## Asymtek

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**Model:** Axiom™ X-1020 **Intro:** Jan. 2002  
**Footprint:** 1100 x 1443mm (43" x 57")\* **Principal Use:** Inline production  
**Applications:** Adhesives, encapsulants, underfills, dots  
**Dispense Area:** 432 x 452mm (17" x 17.8") Pump-configuration dependent  
**Vision System:** Pattern recognition with blue & red LEDs  
**Unique Features:** CAN bus structure with local µP control. Integrated needle calibration module that can support both single and dual valve small dot dispensing for a wide variety of fluids, processes and applications.

## Creative Automation Company (Dispensing Division)

11641 Pendleton St., Sun Valley, CA 91352  
 ☎ 818.767.6220 ☎ 818.767.1243  
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 Dispensing Division  
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**Model:** Champion 8300 **Intro:** Dec. 2000  
**Footprint:** 1120 x 1320mm (44" x 54") **Principal Use:** Production  
**Applications:** Encapsulants, underfill, dam and fill, conductive epoxy, surface mount adhesive and solder paste  
**Dispense Area:** 457 x 508mm (18" x 20") **Vision System:** Feature recognition  
**Unique Features:** Digital dispensing with pixel size down to 0.005"

## Dias Automation HK Ltd.

Unit A7, 3d Floor, Block A, Merit Industrial Bldg.  
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 ☎ +852.2333.6298 ☎ +852.2764.0187

[www.diasautomation.com](http://www.diasautomation.com)

No data—consult manufacturer

## GPD GLOBAL

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**Model:** MicroMax, MicroMax II **Intro:** June 2001 (MicroMax)

**Footprint:** 930 x 1270mm (36.5" x 47")  
**Principal Use:** Inline production, batch, R&D depending on configuration  
**Applications:** MicroVolume solder paste, cond. adhesives, underfill, dam and fill, globtop, SMT adhesive, multifunctional place with dispense, die attach adhesives, CMOS image assembly, heat dissipation attachment  
**Dispense Area:** 305 x 305mm (12" x 12")  
**Vision System:** 2D pattern recognition standard; optional: ClearVu with programmable zoom and focus  
**Unique Features:** Automatic needle cleaning, process enhancement of backlit calibration station

This listing is based on data supplied by the individual manufacturers, but is not meant to be all-inclusive as to product or company. For systems introduced before 2000, please consult manufacturer's Website. *Chip Scale Review* assumes no liability for omissions, typographical errors or misprints. For most current information, please contact the manufacturer. **Boldface** type indicates issue advertiser.  
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### KEY

☎ Phone  
 ☎ Fax  
 🏠 Year Founded  
 \* Inches are rounded up

## HESSE & KNIPPS GmbH

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Additional Offices ☎ 408.436.9300 2305 Paragon Dr., San Jose CA 95131

**Model:** DJ330/335 **Intro:** 2002 (second generation)  
**Footprint:** 750 x 1250mm (29.5" x 49")  
**Principal Use:** Consult manufacturer  
**Applications:** Adhesives, dam and fill, encapsulation, solder paste, silver epoxy, underfill  
**Dispense Area:** X=356mm, Y=457mm, Z=50mm (X=14", Y=18", Z=2")  
**Vision System:** Advanced pattern recognition with oblique and vertical illumination  
**Unique Features:** Dot positional accuracy of ±20 microns and repeatability of ±10 microns; up to five interchangeable tools or valves on a single head

## NEWPORT MRSI GROUP

101 Billerica Ave., Bldg. 3, North Billerica, MA 01862  
 ☎ 978.667.9449 ☎ 978.667.6109  
 🏠 1984 [www.mrsigroup.com](http://www.mrsigroup.com)

Dan Crowley  
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**Model:** MRSI 175 Uf  
**Footprint:** 889 x 990mm (35" x 39")  
**Applications:** Encapsulants, underfills  
**Vision System:** 2D, pattern recognition  
**Unique Features:** High speed, high accuracy, automatic dispenser with dual lane capability and positive displacement pumps for high performance for semiconductor packaging applications.

## Model: MRSI 175 Ag

**Footprint:** 889 x 990mm (35" x 39")  
**Applications:** Adhesives, underfills, die attach, solder paste  
**Vision System:** 2D, pattern recognition  
**Unique Features:** Process control and dispensing capability for applications including microwav, optical, hybrid, MCM, and IC packaging. Can be configured with 2 positive displacement pumps or 1 positive displacement pump and 1 stamp head.

## SPEEDLINE TECHNOLOGIES (formerly Cookson Electronic Equipment)

16 Forge Park, Franklin, MA 02038  
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 Product Marketing Manager  
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**Model:** XyflexPro HVB **Intro:** Dec. 2003  
**Footprint:** 2427 x 2103mm (96" x 83")  
**Principal Use:** High-volume batch production  
**Applications:** Underfill  
**Dispense Area:** Four dispense areas of 368 x 324mm (14.5" x 12.75")  
**Vision System:** Pattern recognition; other: add. fiducials and chip-edge detection  
**Unique Features:** Patented conveyor-less material handling system, dual independent dispense heads

## Model: XyflexPro DLM **Intro:** July 2002

**Footprint:** 1270 x 1440mm (50" x 56.7")  
**Principal Use:** Inline production, batch, R&D  
**Applications:** Adhesives, dam and fill, encapsulants, silver epoxy, solder paste  
**Dispense Area:** 330 x 254mm (13" x 10")  
**Vision System:** Pattern recognition; other: add. fiducials and chip-edge detection  
**Unique Features:** Dual asynchronous conveyors with three heat zones each, increased dispense head utilities